



Device Material Content

5555 NE Moore Ct. Hillsboro OR 97124 custreq@latticesemi.com					Package Code: BBG400		Assembly: ASEK Size (mm): 17 x 17 Lead pitch (mm): 0.8 MSL: 3 Reflow max (°C): 260	
July, 2026	Package: Total Device Weight		400 caBGA 0.719 Grams		Products: LCMXO4-110			
	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (g)	Substance	CAS #	% of Subst.	Notes / Assumptions:
Die	1.665%	0.0120	1.665%	0.0120	Silicon chip	7440-21-3	100.00%	
Mold Compound	55.597%	0.3999	48.648% 3.614% 3.058% 0.278%	0.3499 0.0260 0.0220 0.0020	Silica Epoxy resin Phenol Resin Carbon Black	60676-86-0 - - 1333-86-4	87.50% 6.50% 5.50% 0.50%	Mold Compound: Kyocera KE-G1250AHT
D/A Epoxy	0.600%	0.0043	0.516% 0.035% 0.030% 0.006% 0.011% 0.001%	0.00371 0.00026 0.00021 0.00004 0.00008 0.00001	Silver (Ag) 2,2-dimethyl-1,3 Propanediyl Bismethacrylate A mixture of: 4-allyl-2,6-bis(2,3-epoxypropyl)phenol Perfluoropolyoxyalkane ether 2-[[2,2 bis[[[(1-oxoallyloxy)methyl]butoxy)methyl]-2-ethyl-1,3-propanediyl diacrylate bis(4-tert-butylcyclohexyl) peroxydicarbonate	7440-22-4 1985-51-9 - 925918-64-5 94108-97-1 15520-11-3	86.09% 5.92% 4.92% 1.00% 1.88% 0.19%	Die attach epoxy: Henkel 2100A
Wire	0.390%	0.0028	0.379% 0.010% 0.001%	0.0027 0.0001 0.00001	Copper (Cu) Palladium (Pd) Gold (Au)	7440-50-8 7440-05-3 7440-57-5	97.20% 2.50% 0.30%	AuPCC+, 0.02mm dia
Solder Balls	15.546%	0.1118	15.002% 0.466% 0.078%	0.1079 0.0034 0.0006	Tin (Sn) Silver (Ag) Copper (Cu)	7440-31-5 7440-22-4 7440-50-8	96.50% 3.00% 0.50%	SAC305
Substrate	10.219%	0.0735	3.270% 6.949%	0.0235 0.0500	BT Resins Glass fiber	- 65997-17-3	32.00% 68.00%	BT Resin CCL-HL832NX-A
Foil	5.240%	0.0377	4.056% 0.997% 0.188%	0.0292 0.0072 0.0014	Copper Nickel Gold	7440-50-8 7440-02-0 7440-57-5	77.39% 19.02% 3.59%	
Solder Mask	10.742%	0.0773	2.526% 4.104% 1.579% 1.579% 0.954%	0.0182 0.0295 0.0114 0.0114 0.0069	Solvent naphtha (petroleum) Phosphin oxide derivative Talc (containing no asbestiform fibers) Epoxy Resin Barium Sulfate	64742-94-5 - 14807-96-6 85954-11-6 7727-43-7	23.52% 38.20% 14.70% 14.70% 8.88%	Solder mask PSR4000 AUS 320
100.00%		0.719	100.000%	0.719	800.00%			

Note:

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